

DESCRIPTION

The MT7830 is a high-PF, non-isolate LED Driver IC. The floating-ground, high-side BUCK topology makes full wave detection possible. The MT7830 works in QRM mode, which improves both of efficiency and EMI performance. Selectable maximum period control is integrated, such that flick can be eliminated while enough demagnetization time is guaranteed.

Various protections such as OVP, OCP, OTP, etc, are embedded to improve reliability.

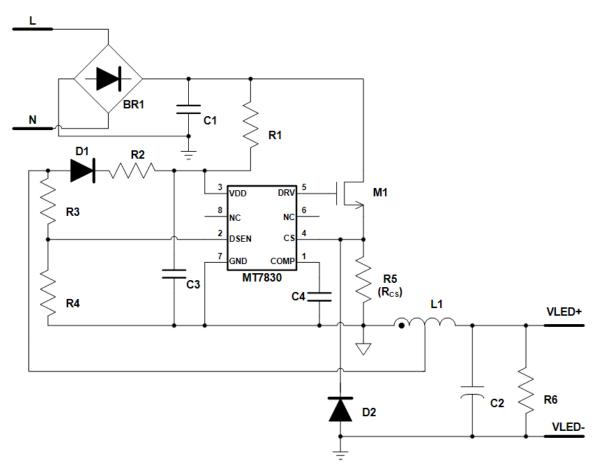
The driving capability of the MT7830 is designed to be insensitive to VDD voltage and soft, with MAXIC proprietary technique. It can help to improve EMI performance greatly.

FEATURES

- Single-stage active power factor correction (PFC > 0.90)
- High accurate LED current (+/-3%)
- Good Line and Load Regulation (+/-2%)
- Quasi-Resonant mode (QRM) operation
- Various protection schemes.
- Power-on soft-start
- Compact package: SOP8

APPLICATIONS

- E27/PAR30/PAR38/GU10 lamp
- T8/T10 LED tube
- Other LED lighting applications



Typical Application Circuit



ABSOLUTE MAXIMUM RATINGS

| VDD Pin Voltage | -0.3V to VDD Clamp |
|---|--------------------|
| COMP/CS/DSEN Pin Voltage | -0.3V to 5V |
| Lead Temperature (soldering, 10 sec.) | 260°C |
| P _{DMAX} (maximum power consumption) | 0.8W |
| Storage Temperature | -55°C to 150°C |

Recommended operating conditions

| Supply voltage | 9V to 28V | | |
|-------------------------------------|----------------|--|--|
| Operating Temperature (Environment) | -40°C to 105°C | | |

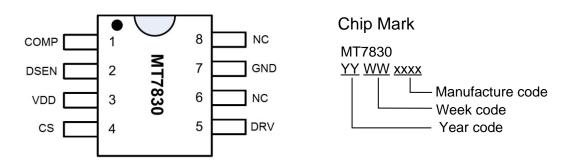
Thermal resistance^①

| Junction to ambient (ReJA) | 128°C/W | | |
|----------------------------|---------|--|--|
| | | | |

Note:

 ReJA is measured in the natural convection at TA = 25°C on a low effective single layer thermal conductivity test board of JEDEC 51-3 thermal measurement standard. Test condition: Device mounted on 2" X 2" FR-4 substrate PCB, 2oz copper, with minimum recommended pad on top layer and thermal vias to bottom layer ground plane.

PIN CONFIGURATIONS



PIN DESCRIPTION

| Name | Pin No. | Description | | |
|------|---------|---|--|--|
| COMP | 1 | Internal EA's output pin. Connect a capacitor to ground for frequency | | |
| | | compensation. | | |
| DSEN | 2 | Feedback pin for inductor zero current crossing detection. | | |
| VDD | 3 | Power Supply pin. | | |
| CS | 4 | Current Sense pin. | | |
| DRV | 5 | External MOSFET drive pin | | |
| NC | 6,8 | No connection pin. | | |
| GND | 7 | Ground pin. | | |

MT7830 Rev. 1. 25



ELECTRICAL CHARACTERISTICS

| (Test condition | s: VDD=15V, TA=25°C unless otherwise stated | l.) |
|-----------------|---|-----|
| | | |

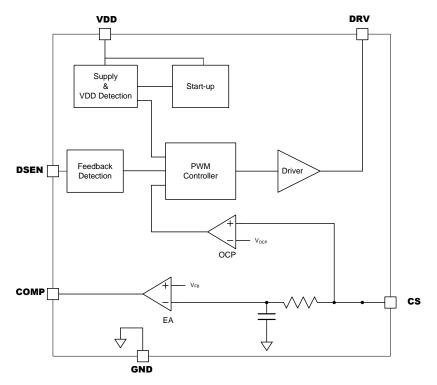
| Symbol | Parameter | Conditions | Min | Тур | Max | Unit |
|----------------------|----------------------------|-----------------------------|-----|-----|-----|-------|
| Start-up (V | 'DD Pin) | | | | | |
| V _{STP} | Start-up Voltage | VDD Ramp-up from 0V | | 18 | | V |
| UVLO | Under Voltage Lockout | VDD Ramp-down | | 9 | | V |
| | Under Voltage Luckout | from (V _{STP} +1V) | | 9 | | v |
| I _{STP} | Start-up Current | VDD=16V | | 25 | | μA |
| OVP1 | Over Voltage | | | 28 | | v |
| 0011 | Protection of VDD | | | 20 | | v |
| ICLAMP | Sinking Current Capability | | | 5 | | mA |
| ICLAMP | to Clamp VDD | | | 0 | | шл |
| Power Sup | ply Current | | - | | | |
| Ι _Q | Quiesent Current | | | 1.0 | | mA |
| Control Lo | op (DSEN pin) | r | - | | | |
| V _{REF-FB} | Voltage Reference for | Close the Feedback | 196 | 200 | 204 | mV |
| V KEF-FB | Feedback Loop | Loop | 100 | 200 | 204 | 111.0 |
| SCP | Threshold of Short Circuit | | | 400 | | mV |
| 001 | Protection at DSEN Pin | | | 100 | | |
| OVP2 | Over Voltage Protection | | | 3.2 | | V |
| UVF2 | of DSEN Pin | | | 5.2 | | • |
| LEB1 | Leading Edge Blank for | | | 2 | | uS |
| | DSEN Pin | | | _ | | |
| MinT | Minimum Switching Period | | | 10 | | uS |
| Current Se | nse (CS Pin) | | | 1 | | |
| OCP | Threshold of Over Current | | | 1.4 | | V |
| | Protection at CS Pin | | | | | v |
| LEB2 | Leading Edge Blank for | | | 300 | | nS |
| | CS Pin | | | | | |
| Thermal Pr | rotection | | | 1 | | |
| OTP | Over Temperature | | | 155 | | °C |
| | Protection | | | | | _ |
| Hys _{-OTP} | Hysteresis of OTP | | | 15 | | °C |
| | rive (DRV pin) | | | | | |
| T _{ON_MAX} | Maximum ON time | | | 24 | | uS |
| T _{ON_MIN} | Minimum ON time | | | 300 | | nS |
| T _{OFF_MAX} | Maximum OFF time | | | 75 | | uS |
| ISOURCE | Driver Max. Source current | | | 200 | | mA |
| I _{SINK} | Driver Max. Sink current | | | 400 | | mA |

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BLOCK DIAGRAM



APPLICATION INFORMATION

The MT7830 integrates power factor correction function and works in Quasi-Resonant Mode (QRM). The LED current can be accurately regulated through sensing the inductor current signal.

Averaged Current Control

The MT7830 accurately regulates LED current through sensing the inductor current signal. The LED current can be easily set by:

$$I_{\text{LED}} = \frac{V_{\text{FB}}}{R_{\text{CS}}}$$

Where V_{FB} (=200mV) is the internal reference voltage and R_{CS} is an external current sensing resistor (Rcs is the R5 in circuit in page1).

Start Up

During start-up, the capacitor at VDD is charged through the resistor which is connected to main

line voltage. The internal control logic starts to work when VDD reaches 18V. The COMP pin is, therefore, pre-charged during this process. The internal control loop is established. Once the voltage of COMP reaches 1.4V, the whole system works in normal operation mode.

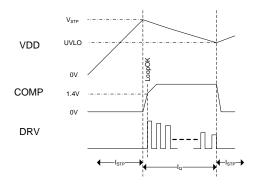


Fig.1 Start up sequence

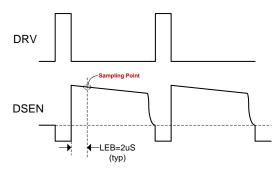
As the VDD goes below 9V, the system is considered to be UVLO, the PWM signal of DRV goes low, and the voltage of COMP is discharged to 0V. The detailed start-up sequence is shown in Fig. 1.

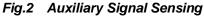


Auxiliary Sensing

The voltage waveform of the inductor is sensed during PWM OFF period for switching logic control, short-circuit protection (SCP).

The DSEN senses the inductor voltage through a resistor divider. The sampling strobe window is 2us LEB (Leading Edge Blanking) time right after the DRV signal is low for better noise immunity as shown in Fig. 2.





Hiccup Mode

Any detected fault conditions, such as, over-voltage (OV), short-circuit (SC) conditions, will force MT7830 into hiccup mode, and PWM signal goes low. VDD is therefore discharged by the MT7830 itself. Then VDD continues to drop below UVLO threshold. A start-up sequence is initiated. If the fault conditions are removed, the LED driver goes back to normal.

The hiccup mode keeps the system at low power

Non-isolated APFC BUCK LED Driver

dissipation state during fault conditions, enhancing system reliability.

Over-voltage Protection

If VDD exceeds 28V three times, OVP is triggered and so the MT7830 gets in Hiccup mode. It is highly recommended to set up the VDD voltage between 11V and 27V.

Short-circuit Protection

The short-circuit protection is triggered if the DSEN voltage is detected below 400mV during OFF period for a continuous time of 5 to 10ms. The MT7830 gets into hiccup mode.

Over-current Protection

The MT7830 immediately turns off the power MOSFET once the voltage at CS pin exceeds 1.4V. This cycle by cycle current limitation scheme prevents the relevant components, such as power MOSFET, inductor, etc. from damage.

Powered by Transformer auxiliary winding

MT7830 can also powered by transformer auxiliary winding to further reduce the system power dissipation. Refer to Fig.3. VDD voltage and DSEN feedback detection can be more accurate by this way.



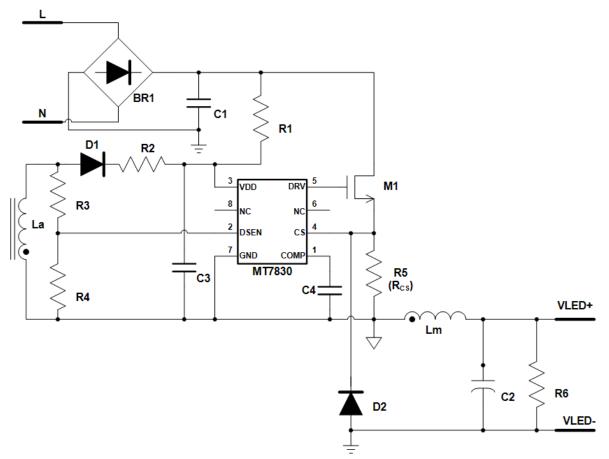
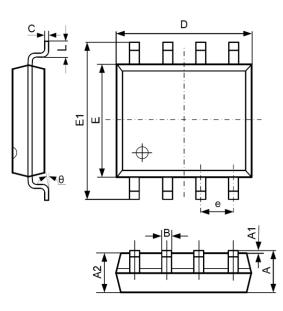


Fig.3 Transformer auxiliary winding to power the VDD



PACKAGE INFORMATION

SOP-8 PACKAGE OUTLINE AND DIMENSIONS



| SYMBOL | DIMENSION IN MILLIMETERS | | DIMENSION IN INCHES | | |
|--------|-----------------------------|-------|------------------------|-------|--|
| | MIN | MAX | MIN | MAX | |
| А | 1.350 | 1.750 | 0.053 | 0.069 | |
| A1 | 0.100 | 0.250 | 0.004 | 0.010 | |
| A2 | 1.350 | 1.550 | 0.053 | 0.061 | |
| В | 0.330 | 0.510 | 0.013 | 0.020 | |
| С | 0.190 | 0.250 | 0.007 | 0.010 | |
| D | 4.700 | 5.100 | 0.185 | 0.201 | |
| E | 3.800 | 4.000 | 0.150 | 0.157 | |
| E1 | 5.800 | 6.300 | 0.228 0.248 | | |
| е | 1.270 TYP | | 0.050 TYP | | |
| L | 0.400 | 1.270 | 0.016 0.050 | | |
| θ | 0° | 8° | 0° 8° | | |

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